



THE SPS Wideband Feedback Processor

A Flexible FPGA-Based Digital Signal Processing Demonstration Platform for Intra-Bunch Beam Stability Studies



Talk Outline

- 1) Introduction
- 2) System Overview
- 3) The Feedback Processor
- 4) Operational Examples
- 5) Upgrades & Next Generation

The SPS





LEIR Low Energy Ion Ring LINAC LINear ACcelerator n-ToF Neutrons Time Of Flight

This project is a collaboration between CERN & SLAC

The CERN Super-Proton Synchrotron:

- Last machine in the LHC injection chain / Normal-conducting
- 6.9km circumference
- Takes Protons from PS at 26 GeV and accelerates them up to 450 GeV for extraction to the LHC
- Beam bunch length:
 - ~4ns @ injection
 - ~2ns @ extraction
- Bucket Width: 5ns
- Bunch Spacing: 25ns (5 buckets)
- LHC Beam: Served up in 4 batches, with each batch consisting of 72 bunches/batch (batches separated by 45 buckets) 288 Bunches Total



Source of images: CERN

Motivation for this Work

- \rightarrow <u>Why</u> are we doing this how we do it and what makes it Challenging?
 - The LHC Injector chain is undergoing an upgrade for increased <u>intensity</u> (more luminosity) / LHC Injectors Upgrade (LIU) project for the High Luminosity LHC (HL-LHC) Program
 - At these higher beam intensities, studies suggest that transverse intra-bunch instabilities in the SPS will limit Lumi
- SPS Transverse instability control 3 Methods:
 - Machine lattice modifications,
 - Vacuum chamber coating (amorphous carbon),
 - Active feedback control
 - Intra-Bunch Stabilization feedback control -- measure, process, and control motion within the 2ns proton bunch
 - <u>How</u>:
 - We measure the motion within the bunch by sampling very fast: 4GSa/s (250ps sample spacing), producing 16 samples (or slices) across 5ns beam bucket width, then compute corrections and apply back onto the beam

SLAC

Engineering Challenges

- → Engineering Challenges: High Bandwidth (1GHz) System Required
 - Wideband Pickups, Kickers, Power Amplifiers
 - Wideband RF processing electronics (Front- and Back- ends)
 - Wideband, High Sampling Rate (4GSa/s) Data converters
 - High-Speed digital electronics for signal processing

- Note: The 1GHz WBFB is for Intra-bunch instability control.
 - This complements the existing SPS transverse damper (lower BW -- 20MHz), which controls coupled bunch instabilities

System Overview – Transverse Feedback



System: AFE / ABE



- Analog Front End:
 - Hybrids combine exponentially tapered stripline pickups, create Δ & Σ outputs, Δ used for vertical displacement measurement
 - Equalizer corrects for phase distortion on Pickup & Cable plant
- Analog Back End:
 - Equalizer performs similar fcn as in AFE
 - Preamps drives signal to power amps in tunnel



System: RF Power Amplifiers

The Kicker is driven by RF Power Amplifiers (Pwr = 1KW, BW = 20MHz...1000MHz)

- Our Application (pulsed mode) requires that the RF Power Amplifier has good transient timedomain performance. This characteristic is typically not specified or tested for by manufacturers who are concerned with modulated CW operation.
- Several different units were evaluated, with R&K Company Limited (Fuji-City, Japan) demonstrating the best performance
- Biggest concern with amp is radiation effects in SPS tunnel / We have fully characterized the new R&K amps to get a baseline on their performance prior to installation at CERN







System: Beam Kicker



- The current stripline kicker at the SPS has 500MHz BW. limits control to lower-order modes (0, 1, 2)
- A design effort for a 1GHz, 1KW kicker was conducted, culminating in a design report (J. Cesaratto, SLAC Toohig fellow). Studied three different kicker designs: Cavity, Stripline and Slotline.
 - The report suggested pursuing the Stripline (better performance at low frequency) and Slotline (slightly lower kick strength, but response is full 1GHz BW) designs.
- The Slotline Design is being fabricated at CERN for installation in 2018



The Feedback Processor



Feedback Processor – Hardware

Commercial FPGA Motherboard





Custom High-Speed ADC Interface Cable Assembly (made by Samtec, Inc.)



Custom DAC Daughterboard



Hardware:

- Mixture of Custom and Commercial HW:
- Enabled a working system to be assembled quickly
- Modular Design (ADC / DAC / FPGA Engine)
- Commercial FPGA Motherboard using Xilinx Virtex-6 (XC6VHX565T largest device in family 567000 logic cells, 864 DSP Slices)
- Custom DAC Daughterboard (designed at SLAC)
 - Uses Maxim MAX19693 12-bit 4 GSa/s DAC
 - Also contains USB Interface, Clock, Trigger & Strobe Circuitry
- ADC:
 - Uses Two Maxim MAX109 2GSa/s (2.2GHz BW) 8-bit ADC Eval Boards interleaved to get 4 GSa/s
 - Custom ADC interface cable developed with and built by Samtec Inc.



Maxim ADC Eval Boards Mounted to Grounding place

SLAC

FB Processor Demo Unit Chassis internal view

Feedback Processor – FPGA Gateware



Feedback Processor – Software



Operational Example 1



2016 SPS MD -- Example of Mode 1 Oscillation Damping

- SPS Setup: single-bunch beam
- Beam Intensity: 2.0E+11 PPB, Q26 lattice (low chromaticity)
- Left-Hand Plot: FB OFF / Injection transient damps, but mode 1 (head-tail) intra-bunch oscillation grows rapidly, charge loss between 400...800 turns
- Right-Hand Plot: FB ON / Injection transient quickly damped down in < 200 turns, No intra-bunch oscillation develops, No charge loss
- Data recorded using WBFS snapshot diagnostic, captures all slices on all turns, DC orbit offset removed post record, data is plotted turn-by-turn

si ac

Operational Example 2

SLAC

2016 SPS MD – Driven Mode Study

- SPS Setup: Multi-Bunch (observing bunch 70)
- Bunch is excited by shifting to positive feedback on turns 3000...6500, 6500 & onward is damping (complete damping in ~1000 turns) / -FB → +FB → -FB
- Surface plot shows Mode 1, some Mode 2
- Spectrogram shows mode 1, some mode 2, hints of mode 3
- Lower Left: Equalized pickup signal shows head-tail structure within the bunch (seeing all 16 slices) over 20 turns

System Upgrades & Next Generation

WBFB Upgrades – Existing 4GSa/s System

- Active DC Orbit Offset removal mechanism
- Use Motherboard DDR3 memory for mult-bunch & many-turn snapshot recording
- Ethernet interface for faster data transfers, remote operation

Next Generation WBFB – 8GSa/s

- Technology has advanced (ADC/DAC/FPGA) to where now am 8GSa/s system is viable
- 8GSa/s :
- Higher BW allows control of more modes (anticipating higher BW backend)
- More samples per bunch provides more detailed diagnostic information
- Processing of shorter bunches (e.g. LHC)
- Enabled different feedback configurations: (e.g. two pickups)

The 8GSa/s effort was funded by the US-Japan Cooperation Program in High Energy Physics

- Prototype system is in development (commercial ADC/DAC/FPGA boards) / Custom ADC Interface board developed
- ADC: Two interleaved 10b, 5GSa/s (3.2GHz BW) Devices
- Custom ADC Interface board developed, awaiting funding for fabrication
- FPGA development, system packaging also awaiting funding

End of Talk Thank you for your attention!

Project Contributors

<u>SLAC</u>:

John Fox Claudio Rivetta John Cesaratto Ozhan Turgut

John Dusatko Jeff Olsen

CERN:

Wolfgang Hofle Urs Wherle Gerd Kotzian Endre Bjorsvik Elias Metral Kevin Li Hannes Bartosik

PI, Project Lead

FB Control, Sim & Modelling, Measurements Toohig Fellow, Sim & Modelling, Kicker Design, Meas Stanford Astro/Aero Grad Student – Optimal Control (thesis topic) / Sim & Modeling System HW/GW/SW Design System SW

BE-RF-FB Group Lead, Lead collaborator System Integration and support Transverse Damper, pickup studies Transverse BQM, SPS system integration Accelerator Physics Accelerator Physics Accelerator Physics